



Emerging metrology requirements for heterogeneous integration and 3D packaging – July 19, 2022



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## Top Stories

### Emerging metrology requirements for heterogeneous integration and 3D packaging

The ability to speed up the deployment of heterogeneous integration in mass production requires new and more frequent types of measurements in key manufacturing processes, including wafer and die bonding as well as lithography. [More>>](#)

### The science of change and preparing for the next unknown

In the last two years, the COVID-19 crisis has shined a light on the growing sense of uncertainty felt across the globe. According to Dr. Vanessa Ahktar of Kotter, this is not an anomaly—according to their research, uncertainty has been the trend for the last few decades. [More>>](#)

### **Sub-fab “operational excellence” drives factory optimization**

In a push to meet the chip supply crunch, fab utilization is at record high of 97%+. In addition, corporate social responsibility (CSR) and sustainability priorities are growing and chip makers are seeking more initiatives to reduce environmental impact. [More>>](#)



## **Tech News**

### **Atomic-level deposition to extend Moore’s Law and beyond**

Moore’s law has driven the semiconductor industry to continue downscaling the critical size of transistors to improve device density. [More>>](#)

### **Novel multi-proton carrier complex as efficient proton conductor at high temperature**

Researchers develop a highly symmetric ruthenium (III) complex with six imidazole-imidazolate groups for efficient high-temperature proton conduction in fuel cells. [More>>](#)

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## Business News

**Silicon carbide cooperation between SEMIKRON and ROHM Semiconductor**  
ROHM's SiC technology empowers SEMIKRON's eMPack for the next generation of electric vehicles. [More>>](#)

**indie Semiconductor formally opens Dresden center of excellence**  
indie Semiconductor, an Autotech solutions innovator, has formally opened its engineering center of excellence (CoE) in Dresden, Germany. [More>>](#)

**SEMI Standards' leaders honored at SEMICON West 2022**  
SEMI, the global industry association that unites the entire electronics manufacturing and design supply chain, announced it honored industry leaders for their outstanding accomplishments in developing Standards for the electronics and related industries. [More>>](#)

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